RD50 MPW2 Test structure

- 60 um x 60 um pixel
- 3x3 pixel array
- central pixel one bond pad
- outer pixels connected together another bond pad





In our setup:



Figure 12. Simplified cross-section of one pixel





Pri w14 precejšnja razlika če fit do 60 V ali do 120 V

Charge collection profile



Čudna oblika depletiranega območja

→ Kako dobro enačba opiše odvisnost d od V in Neff?

→ Bi se dalo to študirati za magisterij npr. s KDetSim ?



 more charge collected at larger y (depth) because length of laser beam inside charge collection region increases because of the shape of the region

$$d = d_0 + \sqrt{\frac{2\varepsilon\varepsilon_0}{e_0 N_{eff}} \cdot V_{sub}}$$

Scan x and y under central pixel



- charge collection region width increases at large depletion depths
- Known effects, seen before in several other samples

Charge from induced signals on outer 8 pixels (without central one)



IR laser direction in E-TCT

Charge collection region extends beyond dimension of the test structure \rightarrow depletion region shape and diffusion from undepleted substrate

Charge from central pixel not included

Charge collection profiles



W11, 120 V



No structure in x directon For higher resistivities

W5: \rightarrow at high bias voltage more charge near pixel edges

- ightarrow at lower bias gaps between pixels ightarrow looks like not depleted
- \rightarrow would be interesting to compare to simulations